
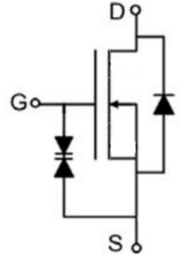


## Description

<b>Features</b> <ul style="list-style-type: none"> <li>● 70V, 0.2A</li> <li>● <math>R_{DS(ON)} &lt; 20\Omega</math> @ <math>V_{GS} = 10V</math></li> <li>● <math>R_{DS(ON)} &lt; 25\Omega</math> @ <math>V_{GS} = 0V</math></li> <li>● Depletion mode</li> <li>● Pb-free lead plating</li> <li>● Halogen free</li> <li>● ESD improved capability</li> </ul>	<b>Application</b> <ul style="list-style-type: none"> <li>● Load Switch</li> <li>● PWM Application</li> <li>● Power management</li> </ul>
 <p>SOT-23-3</p>	 <p>Schematic Diagram</p>

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
VSM0615A-S2	VSM0615A	TAPING	SOT-23-3	7inch	3000	180000

## Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

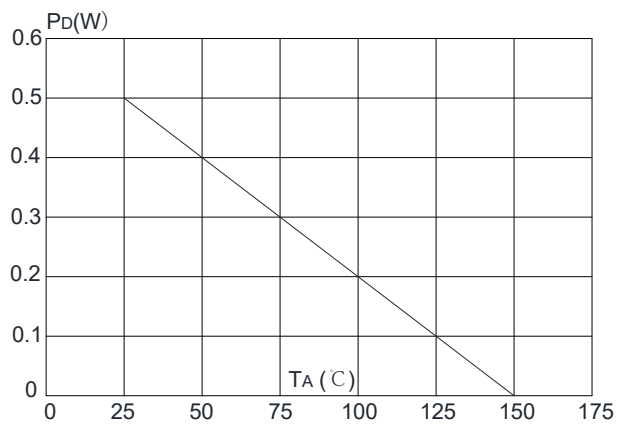
Symbol	Parameter		Max.	Units
V <sub>DSS</sub>	Drain-Source Voltage		70	V
V <sub>GSS</sub>	Gate-Source Voltage		±30	V
I <sub>D</sub>	Continuous Drain Current	T <sub>A</sub> = 25°C	0.2	A
		T <sub>A</sub> = 100°C	0.13	A
I <sub>DM</sub>	Pulsed Drain Current <sup>note1</sup>		0.8	A
dv/dt	Peak Diode Recovery dv/dt		5.0	V/ns
P <sub>D</sub>	Power Dissipation	T <sub>A</sub> = 25°C	0.5	W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient		250	°C/W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C

**Electrical Characteristics** ( $T_J=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = -30V, I <sub>D</sub> =1mA	70	-	-	V
I <sub>D(off)</sub>	Off-state Drain to Source Current	V <sub>DS</sub> =70V, V <sub>GS</sub> = -30V, T <sub>J</sub> =25°C	-	-	1	mA
		V <sub>DS</sub> =56V, V <sub>GS</sub> =-30V, T <sub>J</sub> =125°C	-	-	1	mA
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V	-	-	±1	mA
On Characteristics						
I <sub>DSS</sub>	On-state drain current	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V	0.2	-	-	A
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =20V, I <sub>D</sub> =8μA	-13	-17	-21	V
R <sub>DS(on)</sub>	Static Drain-Source on-Resistance <small>note2</small>	V <sub>GS</sub> =10V, I <sub>D</sub> =0.1A	-	15	20	Ω
		V <sub>GS</sub> =0V, I <sub>D</sub> =0.1A	-	18	25	
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =-5V, f = 1.0MHz	-	65	-	pF
C <sub>oss</sub>	Output Capacitance		-	5	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	1.1	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =35V, I <sub>D</sub> =0.1A, V <sub>GS</sub> =-25V to -30V	-	1.5	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	0.6	-	nC
Q <sub>gd</sub>	Gate-Drain(“Miller”) Charge		-	0.4	-	nC
Switching Characteristics						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DS</sub> =35V, I <sub>D</sub> =0.01A, R <sub>GEN</sub> =6Ω, V <sub>GS</sub> =-25V to -30V	-	9.9	-	ns
t <sub>r</sub>	Turn-on Rise Time		-	55.8	-	ns
t <sub>d(off)</sub>	Turn-off Delay Time		-	56.4	-	ns
t <sub>f</sub>	Turn-off Fall Time		-	136	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current		-	-	0.2	A
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current		-	-	0.8	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>F</sub> =0.2A, V <sub>GS</sub> =-15V	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	V <sub>GS</sub> =-15V, I <sub>F</sub> =0.01A, di/dt=100A/μs	-	245	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	638	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

**Figure 1:** Maximum Power Dissipation vs. Ambient Temperature**Figure 2:** Maximum Continuous Drain Current vs. Ambient Temperature